

# CHO-BOND® 584-208

## TWO COMPONENT ELECTRICALLY CONDUCTIVE EPOXY ADHESIVE SYSTEM



### Customer Value Proposition:

CHO-BOND 584-208 is a two-component, silver filled conductive epoxy adhesive system designed for applications where a strong, highly conductive electrical bond must be achieved. CHO-BOND 584-208 is recommended for applications which require a conductive epoxy with an extended working life such as high volume part dispensing or complex part assembly operations.

Curing of CHO-BOND 584-208 can be achieved in as little as 45 minutes with heat to minimize equipment downtime and increase manufacturing throughput. With a 1:1 weight mix ratio, CHO-BOND 584-208 is easy to handle and use. Typical applications include bonding and grounding of electrical components, cold soldering, and bonding and sealing machined enclosures.



### Features and Benefits:

- Two component
- Silver filler
- Epoxy
- 1:1 Weight mix ratio
- Medium paste
- No VOCs
- Fast heat cure, increases throughput, minimizes equipment downtime.
- Good conductivity 0.002 ohm-cm
- 60 minute working life, works well over wide temperature range, good chemical resistance >1000 psi lap shear, good for permanently bonding surfaces.
- Easy to weigh out and mix.
- May be dispensed out of very small needles, fill small cracks and voids. Can be used on overhead or vertical surfaces
- Minimal shrinkage, no permits or ventilation required

### Contact Information:

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## CHO-BOND 584-208 - Product Information

**Table 1 Typical Properties**

| Typical Properties  | Typical Values  | Test Method           |
|---|---|-----------------------|
| Polymer   | Epoxy   | N/A                   |
| Filler  | Silver  | N/A                   |
| Mix Ratio, A : B (by weight)                                | 1 : 1   | N/A                   |
| Color   | Silver  | N/A (Q)               |
| Consistency   | Medium Paste  | N/A (Q)               |
| Maximum DC Volume Resistivity (Cure Cycle 1)                | 0.002 ohm-cm  | CHO-95-40-5101* (Q/C) |
| Minimum Lap Shear Strength (Cure Cycle 1)                   | 1000 psi (6895 kPa)   | CHO-95-40-5300* (Q/C) |
| Specific Gravity (Room Temp Cure)                           | 2.6   | ASTM D792 (Q/C)       |
| Hardness (Cure Cycle 1)                                     | 80 Shore D  | ASTM-D2240 (Q)        |
| Continuous Use Temperature                                  | - 62°C to 100°C (-80°F to 212°F)  | N/A (Q)               |
| Elevated Temperature Cure Cycle                             | <b>Cure Cycle Option 1:</b><br>0.75 hour @ 100°C (212°F)<br><b>Cure Cycle Option 2:</b><br>2.0 hours @ 65°C (150°F) | N/A                   |
| Room Temperature Cure                                       | 24 hours  | N/A (Q)               |
| Working Life  | 1.0 hours   | N/A (Q)               |
| Shelf Life, unopened  | 9 months @ 25°C (77°F)  | N/A (Q)               |
| Minimum thickness recommended                               | 0.001 in (0.03 mm)  | N/A                   |
| Maximum thickness recommended                               | None  | N/A                   |
| Volatile Organic Content (VOC)                              | 0 g/l   | Calculated            |
| Typical Coverage Area at 0.010" Thick per Pound (454 grams) | 10,500 in <sup>2</sup> (67,742 cm <sup>2</sup> )  | N/A                   |

**Note:** N/A – Not Applicable, [Q/C] - Qualification and Conformance Test, [Q] - Qualification Test

\* This test Method is available from Parker Chomerics.

**Table 2 Ordering Information**

| Product          | Weight (grams) | Packaging                                     | Part Number     | Primer Included |
|------------------|----------------|---|-----------------|-----------------|
| CHO-BOND 584-208 | 85             | 2 component, 4 fluid ounce polypropylene kit  | 50-00-0584-0208 | Not required    |
|                  | 454            | 2 component, 16 fluid ounce polypropylene kit | 50-01-0584-0208 | Not required    |

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

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